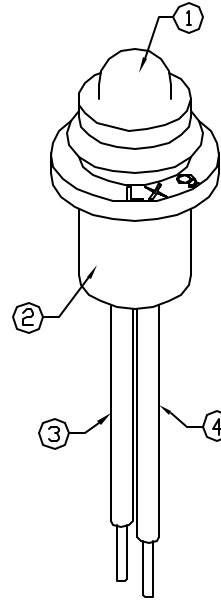
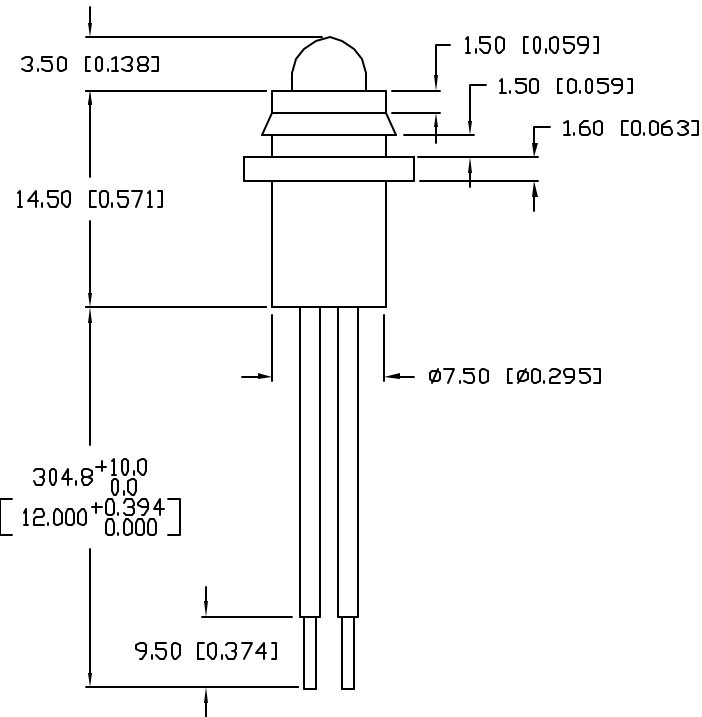
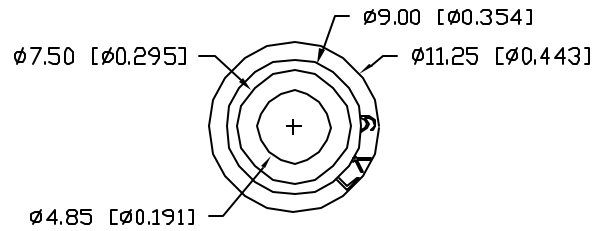


UNCONTROLLED DOCUMENT

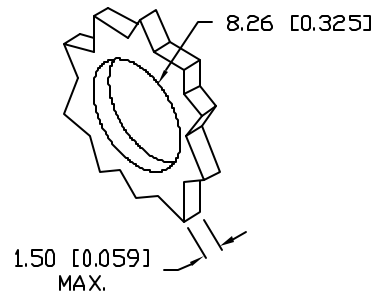
PART NUMBER
SSI-LXH9ID-300

REV.
B

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10786.	9.12.01
B	E.C.N. #10BRDR. & REDRAWN IN 3D.	1.8.02



PANEL CUTOUT



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635		nm	
FORWARD VOLTAGE		2.0	2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		40		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	RED DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$

* $t < 10\mu\text{s}$

NOTES:

1. SSL-LX509F3ID, RED LED.
2. SSH-LXH9, BLACK RUBBER HOUSING.
3. ANODE LEAD: LXP-WST24RDT0C, 24 AWG STRANDED, RED INSULATION, CUT 310mm LONG, STRIP 2mm & 9.5mm.
4. CATHODE LEAD: LXP-WST24BLT0C, 24 AWG STRANDED, BLACK INSULATION, CUT 310mm LONG, STRIP 2mm & 9.5mm.
5. CRIMP WIRE LEADS TO LED LEADS.

UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.=^{+DECIMAL PRECISION}-0.00 MAX.=^{+0.00}-DECIMAL PRECISION

REV.	PART NUMBER
B	SSI-LXH9ID-300

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T-5mm 635nm RED LED PANEL INDICATOR,
RED DIFFUSED LENS, 12" WIRE LEADS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC	CHECKED BY:	APPROVED BY:	DATE: 8.6.01 PAGE: 1 OF 1 SCALE: N/A
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